

OP5650XG Specifications

Product name	OP5650XG
CPU	2nd Generation Intel® Xeon® Scalable Processors Available with the following configuration: <ul style="list-style-type: none"> • 4 Cores - Intel® Xeon® 3.8 GHz • 8 Cores - Intel® Xeon® 3.8 GHz • 16 Cores - Intel® Xeon® 3.3 GHz • 4 Cores - Intel® Xeon® 2.60GHz
FPGA	Xilinx® Artix®-7 FPGA, 200T
I/O lines	256 lines, routed to 8 analog or digital, 16 or 32 channel, conditioning modules
High-speed communication ports	4 SFP sockets, up to 5GBps
Network Controllers	Dual LAN with 1GbE 88E1512
I/O connectors	4 panels of 4 DB37F connectors
Monitoring connectors	4 panels of RJ45 connectors
PC interfaces	Standard PC connectors (monitor, keyboard, mouse, and network)
PCIe slots	6 onboard PCIe slots. 4 or 5 of these slots are available for third-party cards or riser boards depending on CPU configuration.
Hard disk	512 GB SSD
Memory	32 GB DRAM
Power supply	Input: 100-240VAC, 50-60Hz, 8A-4A Power: 600W
Dimensions	22.27 x 47.7 x 49.3cm (8.75" x 18.8" x 19.4") HxWxD
Weight	17kg (37.5 lbs)
Operating temperature	10 to 35°C (50 to 95°F)
Storage temperature	-55 to 85°C (-67 to 185°F)
Maximum rated ambient temperature	35°C (95°F)
Relative humidity	10 to 90% non-condensing
Maximum altitude	2000 m (6562 ft.)

Environmental

Intended use	For Indoor use only
Ventilation requirements	Do not block vents on the unit. Allow sufficient ventilation space around the unit (recommended 6" at sides and rear) when not mounted in a standard rack.
Operating temperature	10 to 35°C (50 to 95°F)
Storage temperature	-55 to 85°C (-67 to 185°F)

Relative humidity	10 to 90% non-condensing
Maximum altitude	2000 m (6562 ft.)
Pollution	Degree 2